MCL4148

150mA Surface Mount Switching Diode- 100V

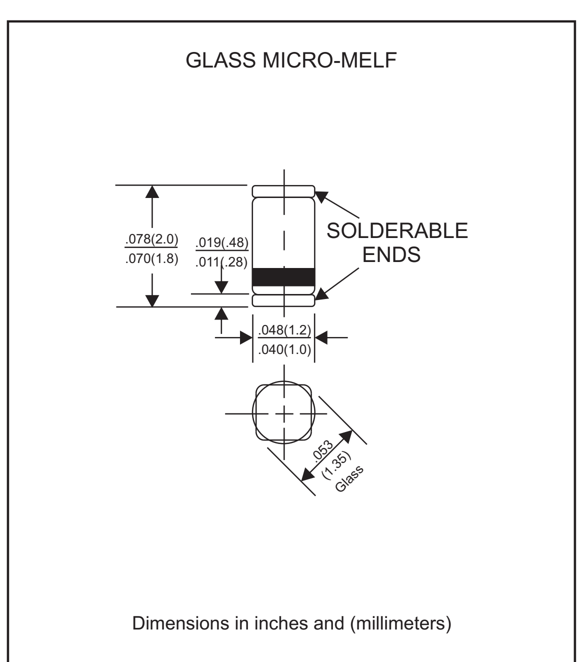
Features

- Fast speed switching.
- For general purpose switching application.
- High conductance.
- Hermetically sealed glass
- Silicon epitaxial planar chip.
- Lead-free parts meet RoHS requirments.

Mechanical data

- Case : GLASS MICRO-MELF
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.013 gram

Package outline



Maximum ratings and Electrical Characteristics (AT T_A=25°C unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Repetitive peak reverse voltage		V_{RRM}			100	V
Reverse voltage		V_R			75	V
Peak forward surge current	t_p = 1 s	I_{FSM}			500	mA
Forward current		I_F			300	mA
Average forward current		I_{FAV}			150	mA
Power dissipation		P_V			500	mW
Junction temperature		T_J	-55		+150	°C
Storage temperature		T_{STG}	-65		+150	°C
Forward voltage	I_F = 10 mA	V_F		0.86	1.00	V
Reverse current	V_R = 20 V	I_R			25	nA
	V_R = 20 V , T_J = 150°C	I_R			50	uA
	V_R = 75 V	I_R			5.0	uA
Diode capacitance	V_R = 0 V , f = 1MHz	C_D			4.0	pF
Reverse recovery time	I_F = 10 mA , V_R = 6V , I_{RR} = 0.1 X I_R , R_L = 100Ω	t_{rr}			4.0	ns

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Rating and characteristic curves (MCL4148)

Fig.1 ADMISSIBLE REPETITIVE PEAK FORWARD CURRENT VERSUS PULSE DURATION

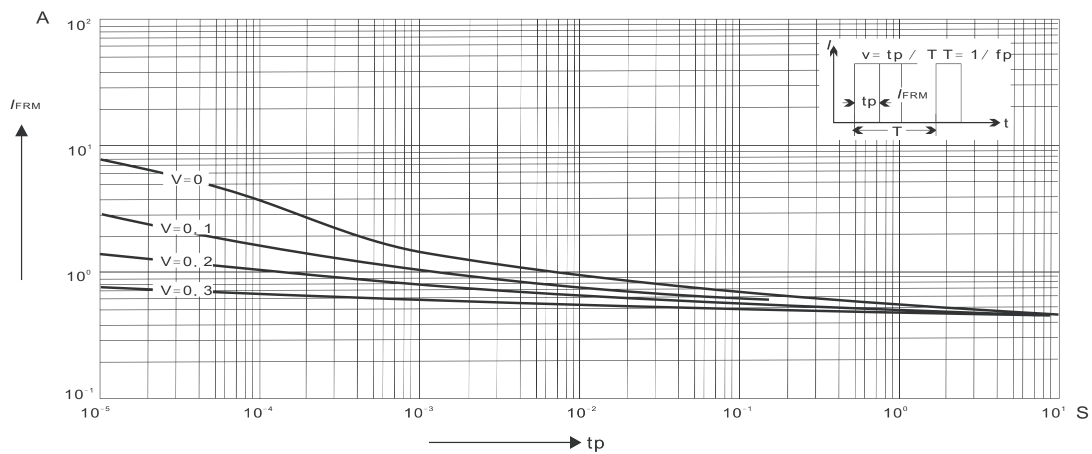


Fig.2-DYNAMIC FORWARD RESISTANCE VERSUS FORWARD CURRENT

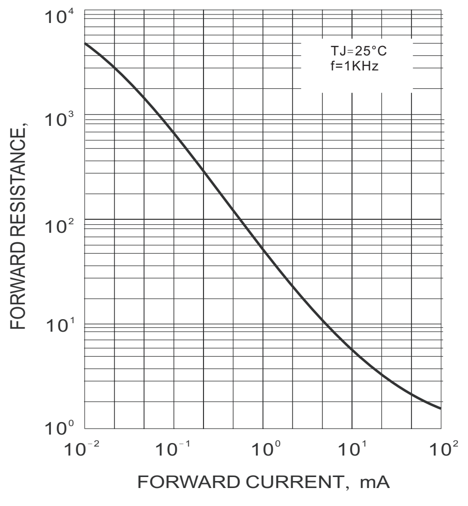


Fig.3 FORWARD CHARACTERISTICS

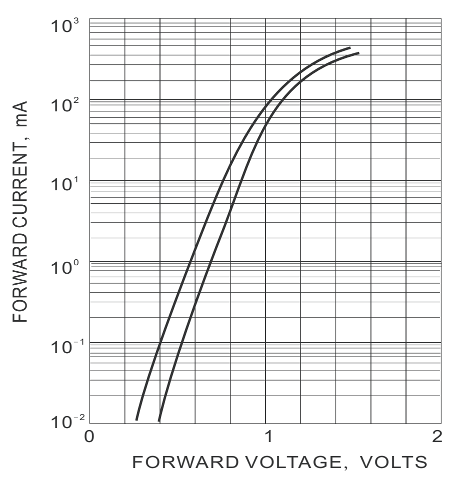


Fig.4 DERATING CURVE

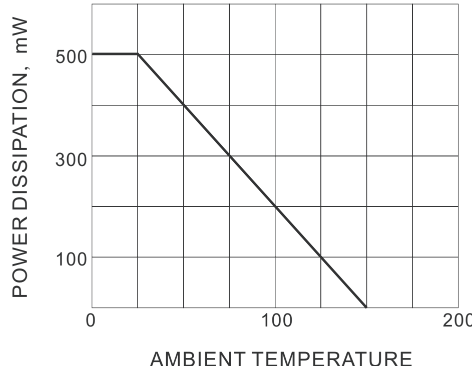
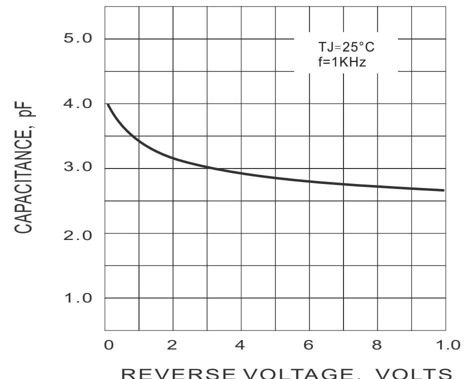


Fig.5 TYPICAL JUNCTION CAPACITANCE



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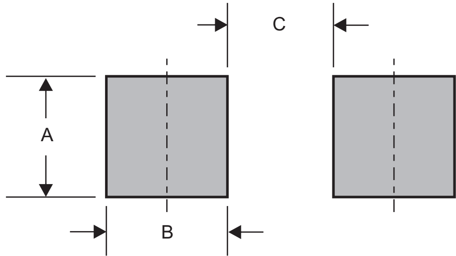
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode	1 2	1 2

Marking

Type number	Marking code
MCL4148	cathode band only

Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
MICRO-MELF	0.055(1.40)	0.024(0.60)	0.051(1.30)

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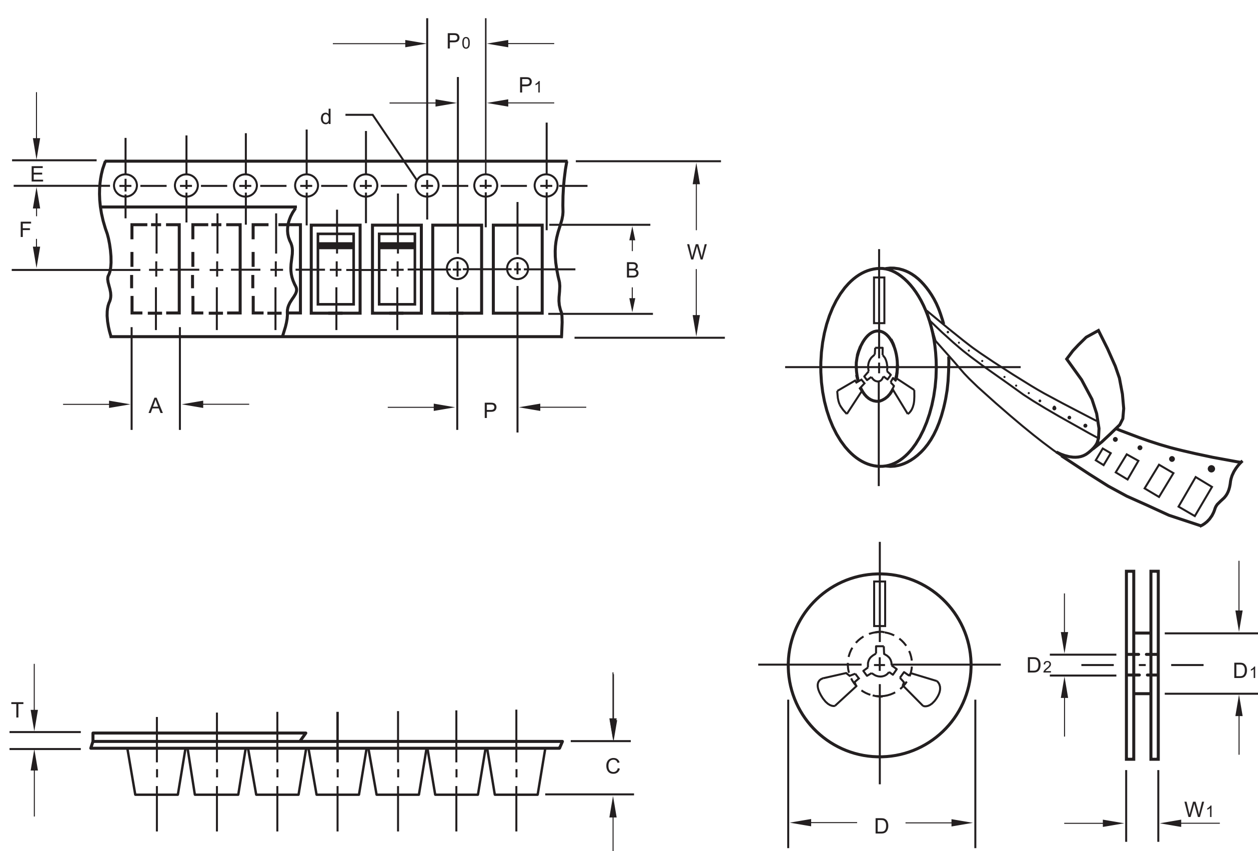
Packing information



unit:mm

Item	Symbol	Tolerance	MICRO-MELF
Carrier width	A	0.1	2.00
Carrier length	B	0.1	3.70
Carrier depth	C	0.1	1.80
Sprocket hole	d	0.1	1.50
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D_1	min	50.00
Feed hole diameter	D_2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P_0	0.1	4.00
Embossment center	P_1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	8.00
Reel width	W_1	0.1	11.40

Note:Devices are packed in accor dance with EIA standar RS-481-A and specifications listed above.

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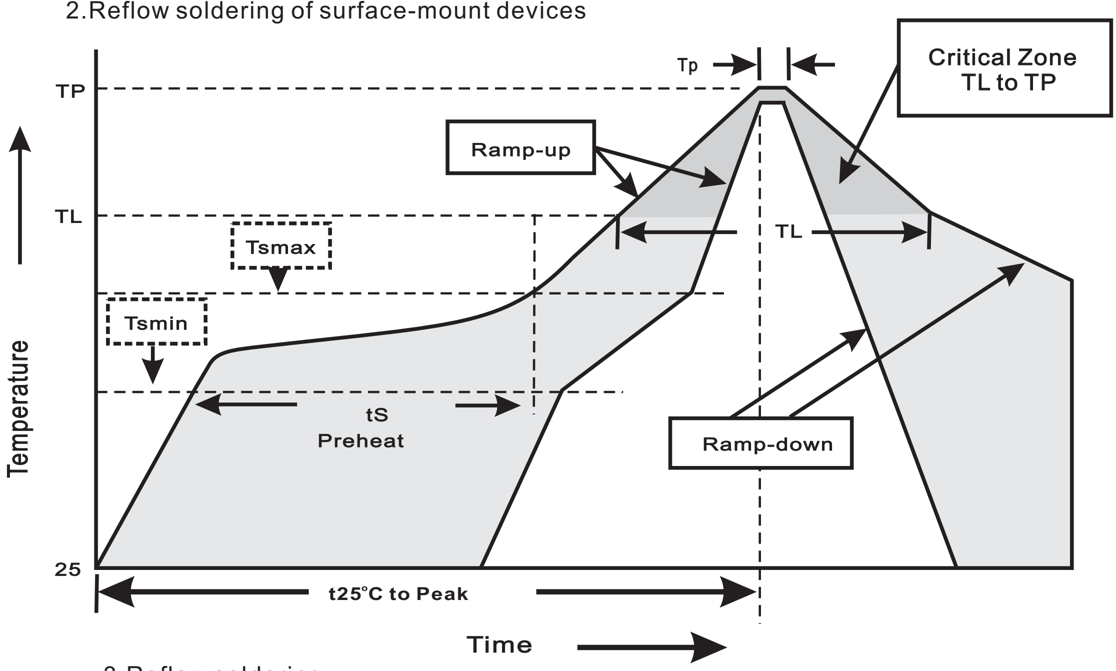
Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
GLASS MICRO -MELF	7"	2,500	4.0	25,000	183*183*123	178	382*262*387	200,000	9.6

Suggested thermal profiles for soldering processes

1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T_L to T_P)	<3°C/sec
Preheat -Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(min to max)(t_s)	 150°C 200°C 60~120sec
Tsmax to T_L -Ramp-upRate	 <3°C/sec
Time maintained above: -Temperature(T_L) -Time(t_L)	 217°C 60~260sec
Peak Temperature(T_P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t_P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes